

HTPA32x32dR2L5.0/0.85F7.7

Datasheet for Thermopile Array Sensor with Lens Optic

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Changelog

2018-11-05	Pixelmask corrected; added startup time of 100µs
2018-11-29	Added eHis drawing for L5.0
2018-12-10	Added radiometric radius and accuracy for L2.1
2019-01-11	Added accuracy and erase default values for TRIM registers
2019-03-01	Added handling advice
2019-03-08	Revised L5.0 drawing with index tap width
2019-03-20	Adapted radiometric radius accuracy; revised soldering height
2019-04-24	Drawing for soldering height adapted
2019-07-05	Revised typical and max current consumption
2019-09-26	Added radiometric radius for L4.0
2020-05-11	Adapted soldering recommendations for non SMD
2020-09-05	Added stack buffer recommendation; how to dk to °C; EEPROM link; pixel mask correction
2020-09-17	Added FoV for L1.6
2021-08-12	New order code
2021-11-16	Updated FoV 50 % Sensitivity, added graph for FoV, specified accuracy
2022-04-27	Corrected pinout in circuit schematic
2024-05-02	Revised L1.7 drawing with updated cap design
2024-10-10	Changed storage and operating temperatures
2024-10-10	Added relative humidity
2024-12-18	Updated graphic for optical orientation
2025-01-31	Updated order code, added order code chart w/available options
2025-02-25	Updated storage temperature for L1.9
2025-02-28	Removed sensitivity, CLK and analog output from common specifications
2025-03-18	Corrected Field of View for L1.6, L2.85 and L4.0; changed F-Number for L2.85 from 0.92 to 1
2025-04-14	Corrected pin allocations
2025-08-18	Corrected graphic for pixel orientation; adjusted graph for NETD vs Pixel Distance

2025-10-16	Added max. measurable temperature
2025-11-18	Corrected accuracy specification
2025-03-02	Added calculation formula for CLK_Trim Register

1 Cleaning and Handling of Sensors with Optical Elements

Cleaning of Filter with Isopropyl Alcohol or Acetone

This is the method most universally used for cleaning optical elements with or without coatings. Filters or lenses mounted in our sensors may be cleaned rubbing the surfaces lightly with a clean, soft, all-cotton cloth or cotton swab during immersion in solvent or simply moistened with the solvent. The parts are then immediately wiped dry with another clean, soft, all-cotton cloth or cotton swab.

Cleaning with Detergent and Water

A very mild, non-abrasive detergent (one which does not contain additives) and water may also be used for cleaning optical elements. In general, a detergent and water mixture is an excellent method for removing fingerprints and other smudges. The liquid detergent is first mixed with deionized water (proportions recommended by the manufacturer should be followed). The element is then washed, rinsed, and immediately wiped dry. Use a clean, soft cloth when cleaning and drying. If the part is allowed to dry in air, a permanent stain may result.

Please note:

- Do not use isopropyl alcohol or acetone or detergent if the elements will be mounted in an assembly with a finish, which may be soluble by these solvents.
- Please avoid glass isolation being moistened by solvent.
- If the part is allowed to dry in air, a permanent stain may result.

Handling Advice

Sensors with optical elements deserve special consideration in their handling and care. Ordinarily, filters or lenses are cleaned and inspected prior to shipment. If proper care is exercised during handling cleaning should not be necessary prior to use.

- Wear gloves when handling a sensor or optical element. Lightweight nylon or cotton gloves which are relatively lint-free are recommended.
- Avoid touching the surface of filters and lenses.
- Protect devices from static discharge and static fields.
- Thermopile sensors are electrostatic sensitive devices. Sensors should be handled over an electrostatic protected work area.
- Precautions should be taken to avoid reverse polarity of power supply for sensors with integrated signal processing. Reversed polarity of power supply results in a destroyed unit.
- Sensors should rest preferably in a partitioned container, where the mounted filters or lenses will be not coming into contact with other material.
- During storage optical surfaces should be covered to avoid contamination from the surrounding environment.

- A covered container can eliminate damage during transportation and storage.
- Sensors or optical elements should be stored in a restricted access area to eliminate handling.
- Do not expose the sensors to aggressive detergents such as freon, trichlorethylen, etc.
- Avoid rotating the sensors when they are soldered into a PCB or something similar.
- Shortening of the pins is not suggested. This may cause cracks in the glass of the pins and result in a leakage.
- If this is necessary, a tool for this is recommended. Please contact Heimann Sensor for further information.

Soldering Recommendations

Attention: For all of our array sensors we give no guarantee on the calibration and its performance, if the pins are shortened by the customer. Additionally, **we strongly recommend to not solder the sensor with its back plate directly to a PCB.** This will cause different thermal conductivity compared to air and the measurement results could get worse. **Use a minimum gap between PCB and backplate of 2 mm or more.** The glass of the pins to the back plate can get damage by applying high temperatures (during soldering), which will lead into a lower temperature reading, what cannot be repaired afterwards.

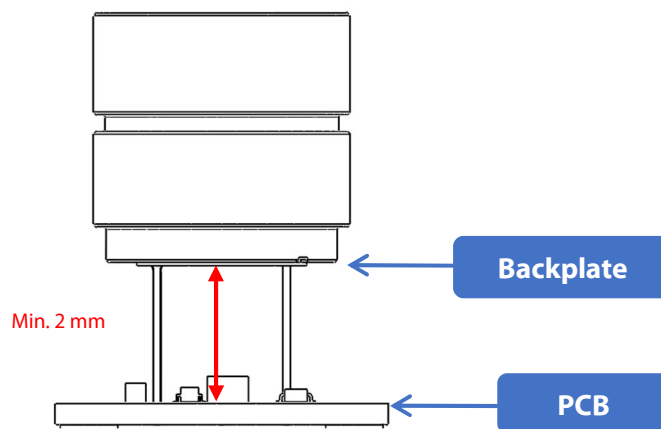


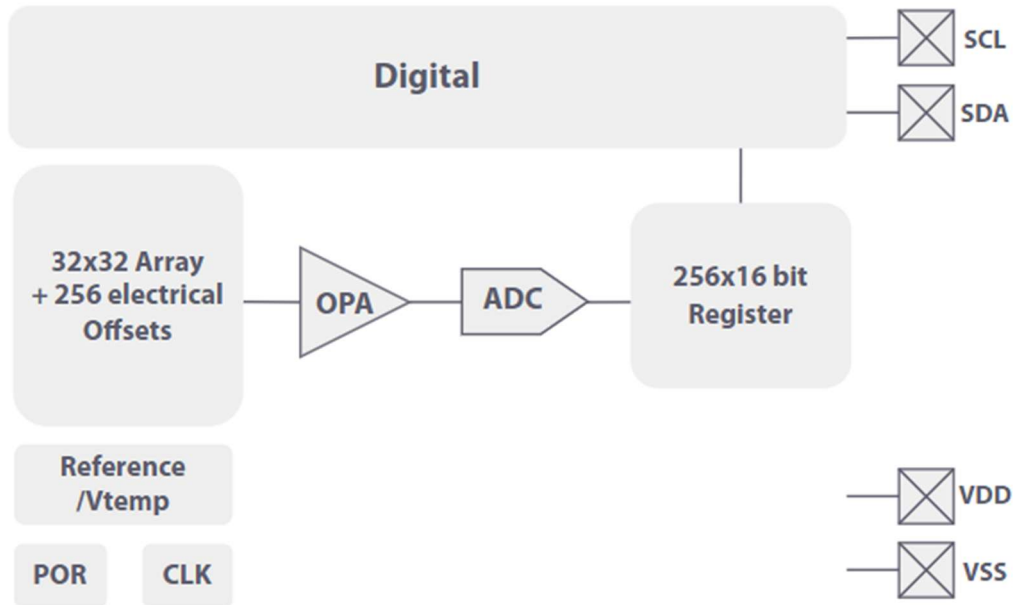
Figure 1: Soldering height

Manual Iron Soldering and Automatic Point-to-Point Iron Soldering

Manual Iron Soldering and Automatic Point-to-Point Iron Soldering methods are allowed for TO packages. It is recommended for through hole applications to shield the package body from soldering heat by PCB or similar.

The soldering iron temperature should be set as low as possible (maximum 350 °C) and should not exceed recommended soldering time (maximum 3 seconds). The minimum distance between the housing body and the liquid solder should be at least 1.5 mm for 350 °C. Reflow soldering is not recommended.

2 Principal Schematic for HTPA32x32d



3 Pin Assignment–Bottom View

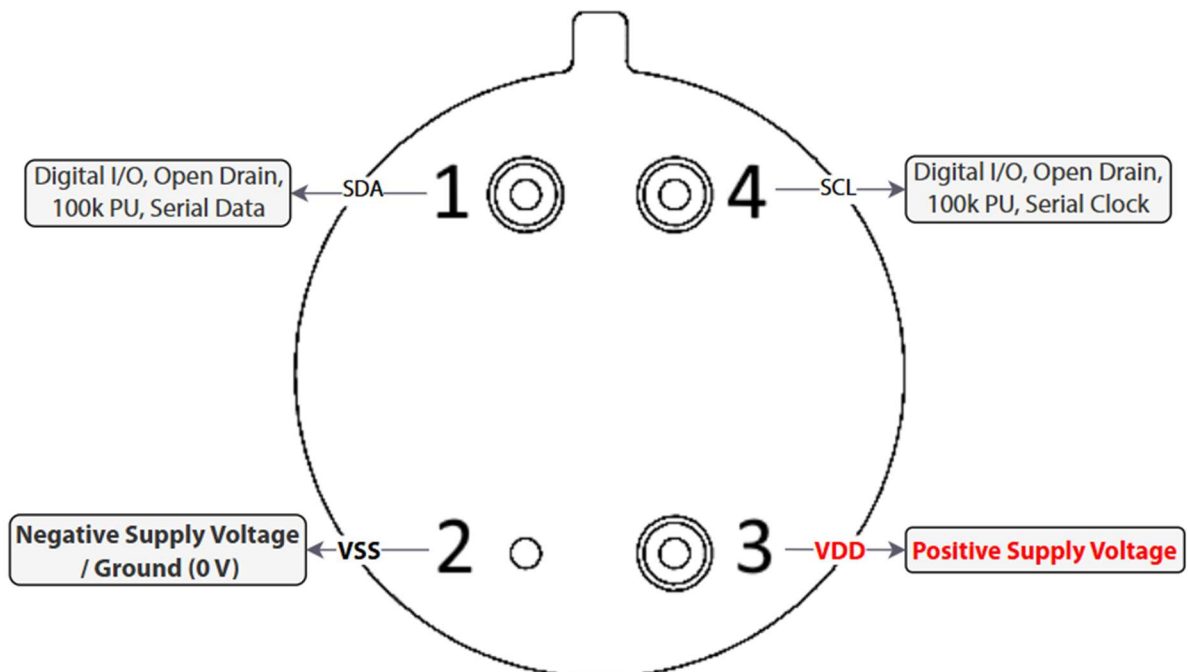
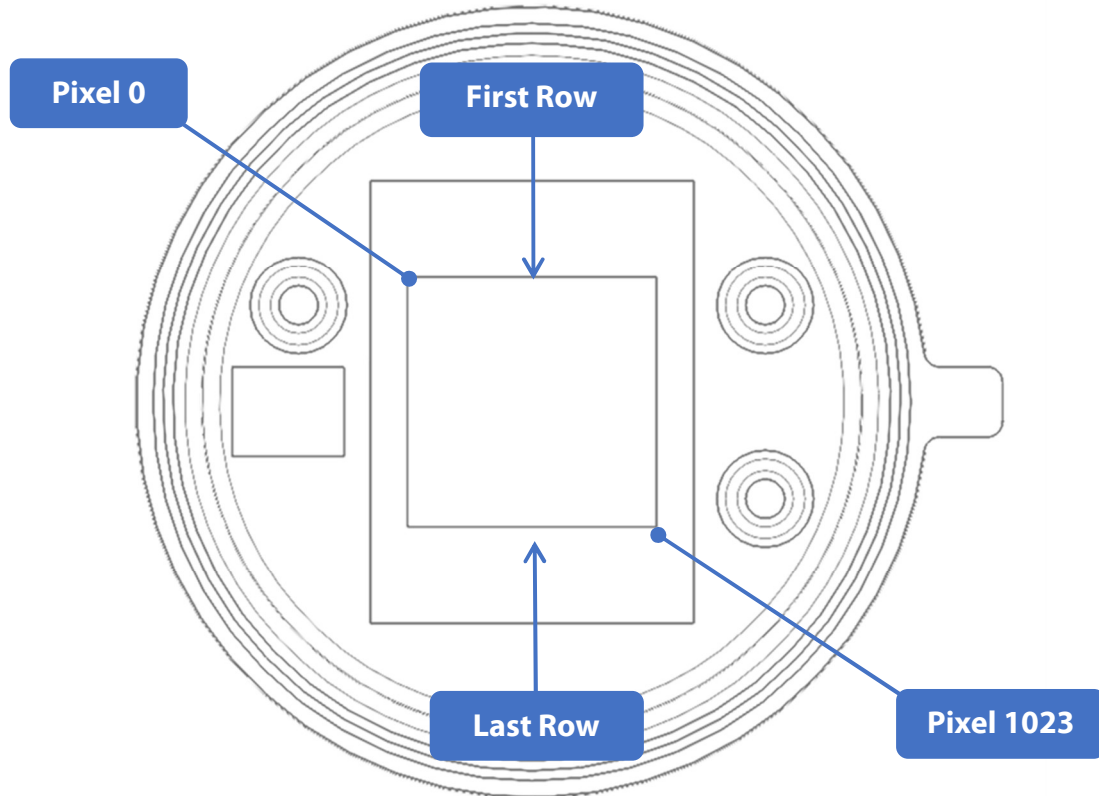
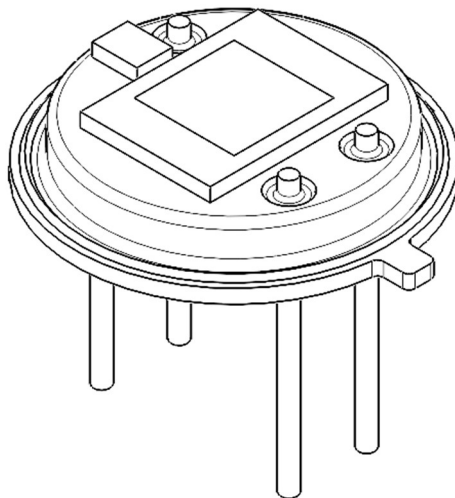


Figure 2: Pin-allocation

4 Optical Orientation



This illustration shows the pixel orientation after mirroring through the lens.



5 Order Code Example

HTPA32x32d	R2	L5.0/0.85	F7.7	e	Hi	M	(UDP)
1	2	3	4	5	6	7	8

		Description
1	Sensor Type	TP Array with 32x32 Pixel For all available HTPA and module combinations contact our support
2	Revision	Silicon revision 2
3	Optics	Focal length/F-Number Focal length: L5.0 = 5.0 mm F-Number: 0.85
4	Filter	F: Filter characteristics Not declared: Broadband AR Coating
5	External Aperture	Not declared: without external aperture e: with external aperture
6	Sensitivity	UHi: increased sensitivity Hi: default sensitivity Not declared: lower sensitivity (greater measurement range)
7	Version	A: Application Set: comes with GUI, housing, power supply C: Calibrated sensor M: Modul: HTPA sensor soldered to PCB, calibrated stream
8	Interface	UDP: Ethernet connection, CAT5 PoE: Power over Ethernet, CAT5* i ² C: 4 Pin Connector* USB: Power and data via USB 2.0** * Interface option is only available for modules (HiM) ** Interface option is only available for Application Set (HiA)

6 Application Note

A pull-up resistor of 4.7 k Ω for the I²C pins (SDA and SCL) is recommended. In addition, adding 100 nF and 47 μ F are improving the stability of the supply voltage.

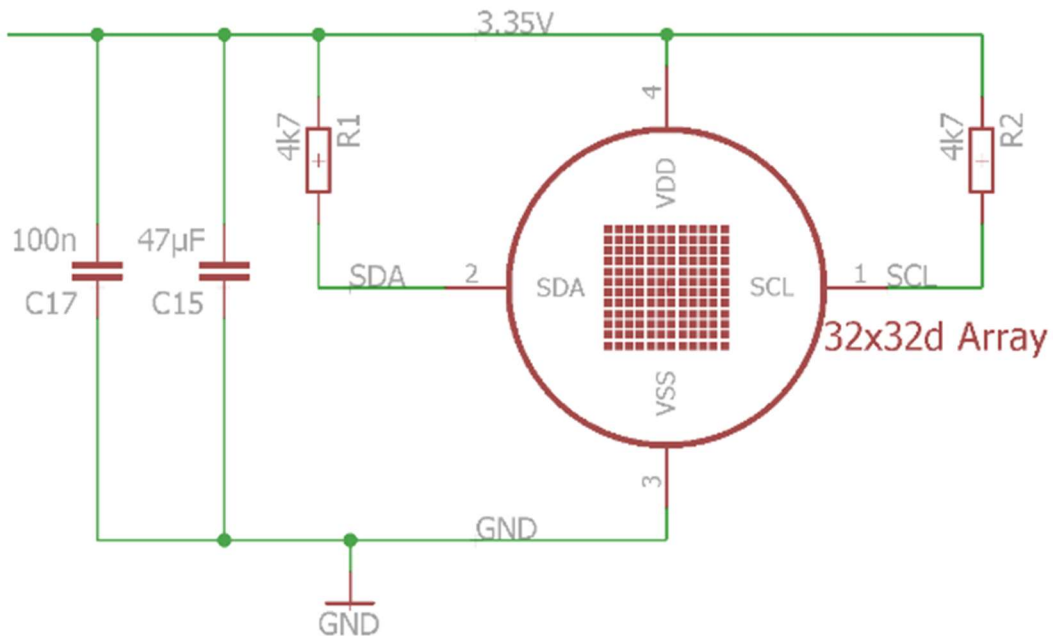


Figure 3: Recommended circuit for operation

The sensor can be powered directly via 3.35 V, if the supply voltage is stable enough, this has to be measured before and tested with the sensor. It is important to not insert any inductor or otherwise the noise will increase.

7 Serial Order of Frame

The sensor is divided into two parts (top and bottom half), which are again separated into 4 blocks. The readout order is shown below for the different blocks.

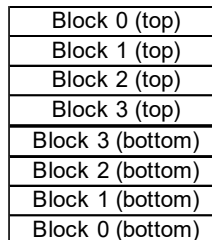


Figure 4: Division of blocks

Whenever a conversion is started, the Block x of the top and bottom half are measured at the same time. Each block consists of 128 Pixel that are sampled fully parallel. The readout order on the bottom half is mirrored compared to the top half so that the central lines are always read last.

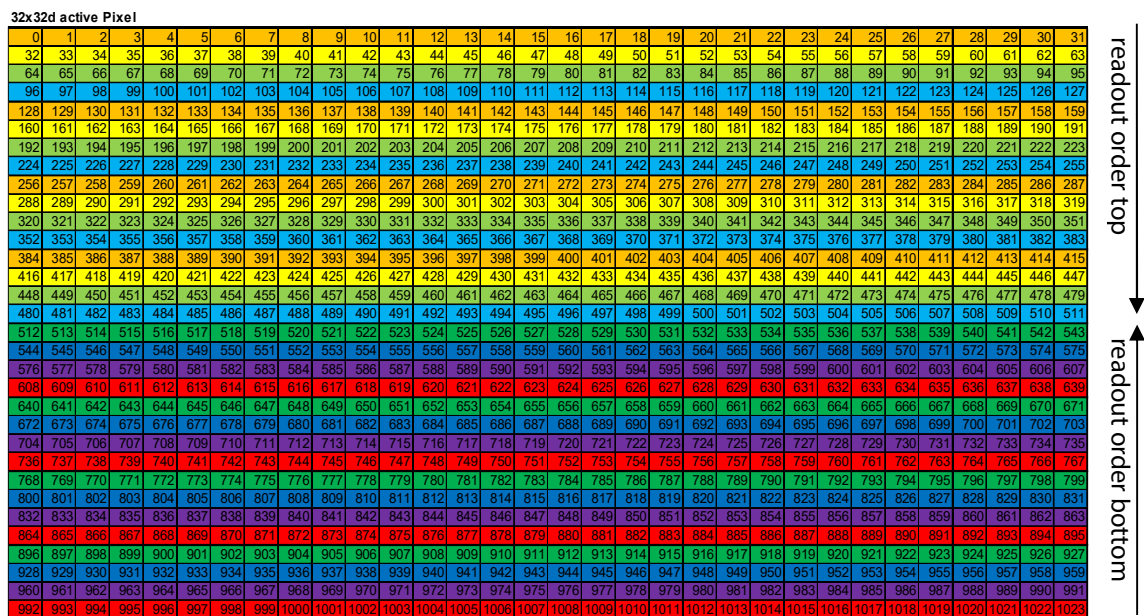


Figure 5: 32x32d readout order for active pixel

The electrical offsets are sampled in parallel for the top and bottom half. The matching rows for the corresponding electrical offsets and active Pixel are marked with the same color. The conversion of the electrical offsets is started by sending the command for the BLIND bit during the start command.

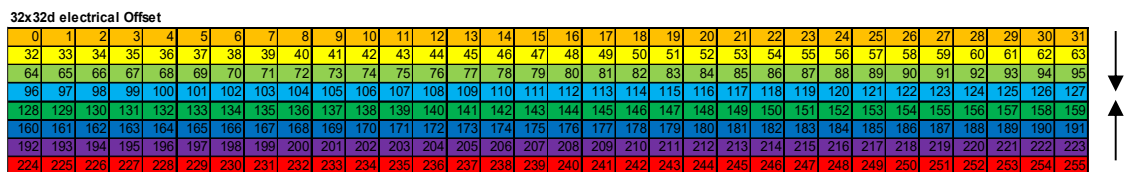


Figure 6: 32x32d readout order for electrical offset

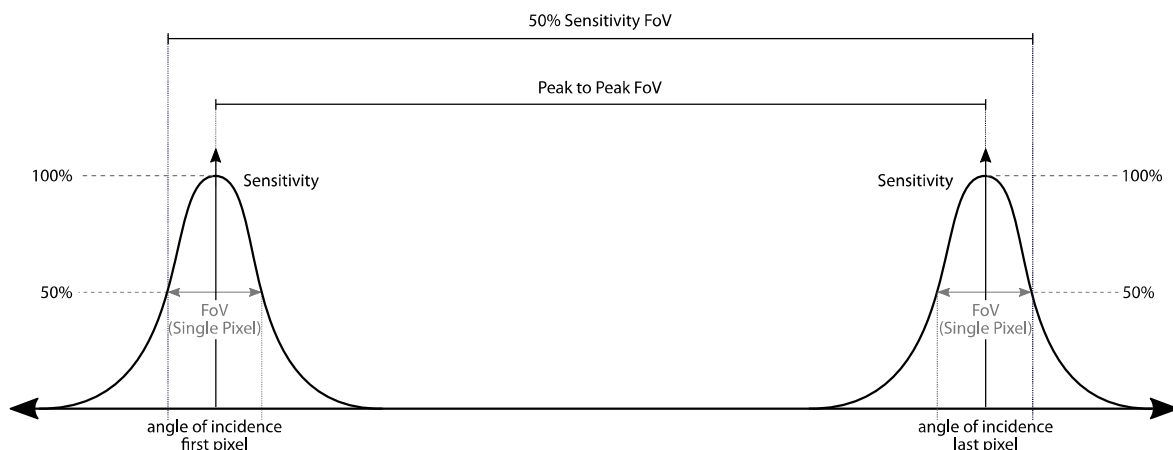
8 Characteristics

8.1 Common Specifications

Technology:	n-poly/p-poly Si
Element Resistance:	approx. 300 kOhms
Thermal pixel time constant:	<4 ms
Digital Interface:	I ² C
EEPROM size:	64 kBit
Pitch:	90 μm
Absorber size:	44 μm
Max. Framerate:	60 Hz
Max. measurable temperature:	1000°C with default settings
(complete frame with maximum I ² C and sensor clock speed and reduced ADC resolution)	

8.2 Optical Characteristics

Focal length:	5.0 mm ("L" equals the focal length of the lens)
F-Number:	0.85
Field of view:	34 x 34 deg (50% sensitivity FoV)



Lens coating:	LWP-Coating 7.7 Cut On (Tr. 5 %): 7.7 μm
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Accuracy:	±3 % or ±3 K (whichever is larger) in the working ambient temperature range of 5° to 50 °C and object temperatures ≤ to 300 °C
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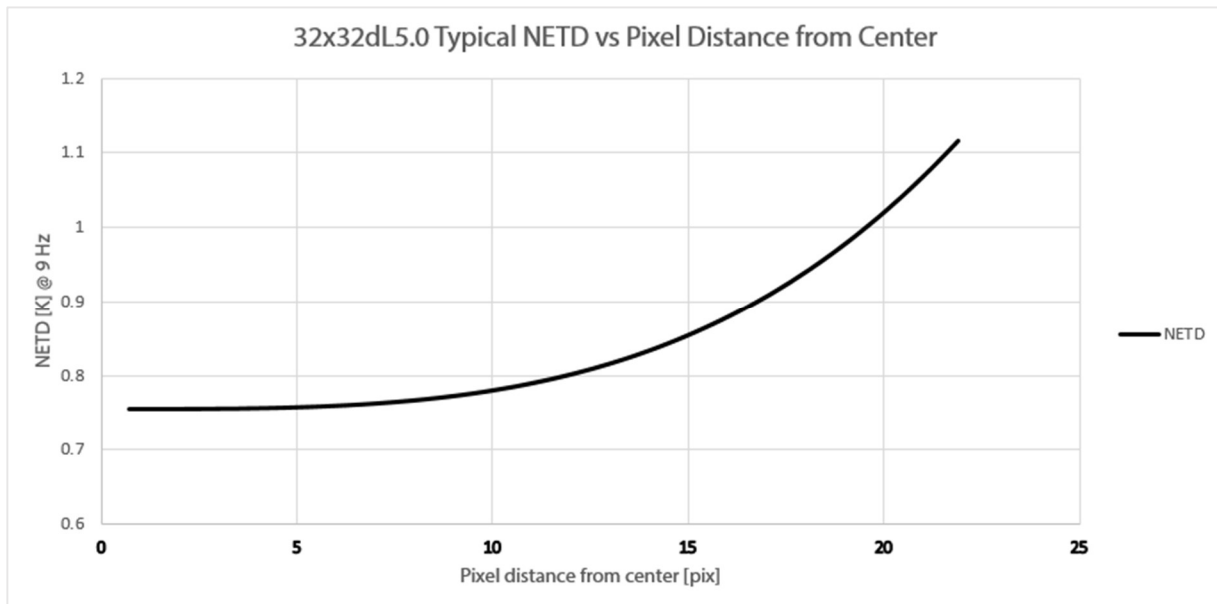


Figure 7: NETD vs Pixel distance

9 Electric Specifications

Table 1: Absolute Maximum Ratings

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Supply Voltage	V_{DD}		-0.3		3.6	V
Voltage at all inputs and outputs	V_{IO}		-0.3		$V_{DD}+0.3$	V
Storage Temperature	T_{STG}		-40		85	Deg. C

Table 2: Operating Conditions

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Supply Voltage	V_{DD}		3.3	3.35	3.6	V
Supply Current (sensor running)	I_{DD}		5.0	6.2	7.4	mA
Supply Current (sensor in idle state)	I_{DD}		4.5	5.8	7.15	mA
Standby Current (sensor in sleep state)	I_{SBY}		7	9	11	μ A
Operation Temperature	T_A		-20		85	Deg. C
ESD-Protection		Human body model	2.0			kV
		100pF + 1k50hm				

Table 3: Electrical Characteristics

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Digital Input						
Internal Clock frequency	F_{CLK}		1	5	13	MHz
Internal I ² C Pull up	R_{PU}		1	100	100	kOhm
BIAS current	I_{BIAS}		1	3	13	μ A
BPA current	I_{BPA}		0.2	1.5	4.0	μ A
Input voltage high	V_{IH}		$0.7 \times V_{DD}$			V
Input voltage low	V_{IL}				$0.3 \times V_{DD}$	V
PTAT						
Temperature range			TBD		TBD	Deg. C
PTAT gradient			328	339	350	K/V

Table 4: Preamplifier / ADC

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Chopper frequency	F _{CHP}			20		kHz
Preamplifier Noise	N _{PA}	at 20 kHz		72		nV/HZ ^{1/2}
Frame rate (Full Array)	FR1		2	9	60	Hz
Frame rate (Quarter Array)	FR4		8	36	240	HZ
ADC pos. Reference	V _{REFP}	REF_CAL 00		1.529		V
		REF_CAL 01		1.442		
		REF_CAL 10		1.355		
		REF_CAL 11		1.268		
ADC neg. Reference	V _{REFN}	REF_CAL 00		0.850		V
		REF_CAL 01		0.901		
		REF_CAL 10		0.968		
		REF_CAL 11		1.056		
ADC resolution	ADC _{LSB}	at 16 Bit	6.5		20.7	μV

10 I²C Timings HTPA32x32d

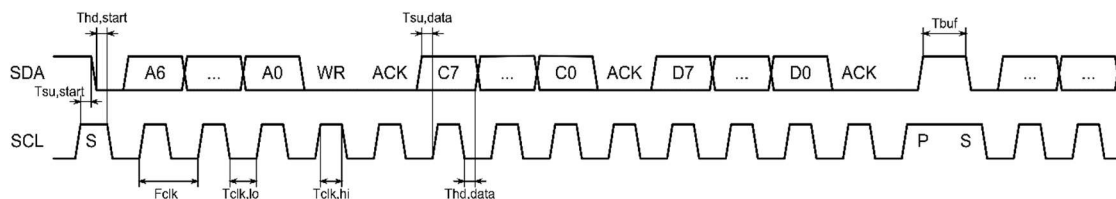


Figure 8: I²C Timings of HTPA32x32d

Table 5: I²C Timings

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
I²C clock frequency	FCLK			400	1000	kHz
Low pulse duration	TCLK,lo		0.50			μs
High pulse duration	TCLK,hi		0.26			μs
Data set up time	TSU,data		0.05			μs
Data hold time	Thd,data		0.00			μs
Start setup time	TSU,start		0.26			μs
Start hold time	Thd,start		0.26			μs
Stop setup time	TSU,stop		0.26			μs
Stop hold time	Thd,stop		0.26			μs
Time between STOP / START	Tbuf		0.50			μs
Time startup (after Power-on-reset)	Tstartup				100	μs
Wakeup time (after sending WAKEUP)	Twakeup				80	μs

11 I²C Communication

The chip uses the **7-bit I²C address 0x1A** for configuration and **sensor** data and the **7-bit I²C address 0x50** to access the internal **EEPROM**. The address byte is followed by a W/R bit and an 8-bit command.

11.1 Write Command

In case of a write access to an internal register the command is followed by the data byte. The chip acknowledges each byte with a low active ACK bit.

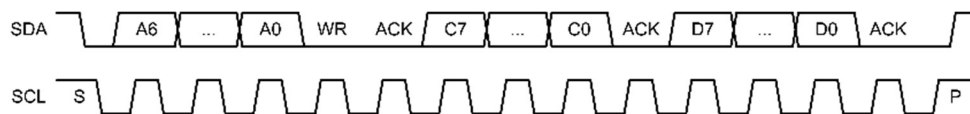


Figure 9: Write Command

11.2 Read Command

To read data from the chip first the address and read command must be sent. After the last ACK a new start-bit (repeated start) and the address with a set read-flag initiates the read sequence. There can be bytes read as many as required. The last byte must be denoted by a not-acknowledge. The shown example below can be used e.g. to get the status register.

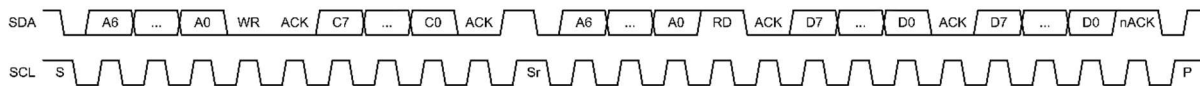


Figure 10: Read Command

11.3 Sensor Commands

The sensor has several registers that can be written and read, they are listed below.

Table 6: Configuration Register (write only)

Addr / CMD	0x1A (7 Bit!) / 0x01							
Config Reg	7	6	5	4	3	2	1	0
Name	RFU		BLOCK		START	VDD_MEAS	BLIND	WAKEUP
Default	0	0	0	0	0	0	0	0

The WAKEUP bit is used to switch on / off the chip and must be set prior all other operations. After the START bit is set the chip starts a conversion of the array or blind elements and enters the idle state (not sleep!), when finished. The BLOCK selects one of the four multiplexed array blocks.

If the BLIND bit is set the electrical offsets are sampled instead of the active pixel and the setting of the BLOCK is ignored.

If VDD_MEAS bit is set the VDD voltage is measured instead of the PTAT value.

RFU means reserved for future use and can be subject to change.

Table 7: Status Register (read only)

Addr / CMD	0x1A (7 Bit!) / 0x02							
Status Reg	7	6	5	4	3	2	1	0
Name	RFU		BLOCK		RFU	VDD_MEAS	BLIND	EOC

If the EOC flag is set a previous started conversion has been finished.

Table 8: Trim Register 1 (write only)

Addr / CMD	0x1A (7 Bit!) / 0x03							
Trim Reg 1	7	6	5	4	3	2	1	0
Name	RFU		REF_CAL		MBIT TRIM			

REF_CAL: selectable amplification

MBIT_TRIM: $m = 4$ to $12 \Rightarrow (m+4)$ bit as ADC resolution

Table 9: Trim Register 2 (write only)

Addr / CMD	0x1A (7 Bit!) / 0x04							
Trim Reg 2	7	6	5	4	3	2	1	0
Name	RFU			BIAS TRIM TOP				

BIAS_TRIM_TOP: 0 to 31 $\Rightarrow 1 \mu\text{A}$ to $13 \mu\text{A}$

This setting is used to adjust the BIAS current of the ADC. A faster clock frequency requires a higher BIAS current setting.

Table 10: Trim Register 3 (write only)

Addr / CMD	0x1A (7 Bit!) / 0x05							
Trim Reg 3	7	6	5	4	3	2	1	0
Name	RFU			BIAS TRIM BOT				

BIAS_TRIM_BOT: 0 to 31 $\Rightarrow 1 \mu\text{A}$ to $13 \mu\text{A}$

This setting is used to adjust the BIAS current of the ADC. A faster clock frequency requires a higher BIAS current setting.

Table 11: Trim Register 4 (write only)

Addr / CMD	0x1A (7 Bit!) / 0x06							
Trim Reg 4	7	6	5	4	3	2	1	0
Name	RFU		CLK TRIM					

CLK_TRIM ranges from 0 to 63 and corresponds the clock frequency F_{CLK} which can be determined via the following formula:

$$F_{CLK} = \left(F_{CLK,min} + \frac{F_{CLK,max} - F_{CLK,min}}{63} \cdot \text{CLK_TRIM} \right) \text{MHz}$$

with

$$F_{CLK,min} = 1 \text{ MHz}$$

$$F_{CLK,max} = 13 \text{ MHz}$$

The measure time depends on the clock frequency settings. One quarter frame takes about:

$$t_{fr4} = \frac{32 \cdot (2^{MBIT} + 4)}{F_{CLK}} \approx 27 \text{ms@5MHz}$$

MBIT is equal to MBIT TRIM in Table 8.

Table 12: Trim Register 5 (write only)

Addr / CMD	0x1A (7 Bit!) / 0x07							
Trim Reg 5	7	6	5	4	3	2	1	0
Name	RFU			BPA TRIM TOP				

BPA_TRIM_TOP: 0 to 31 ⇒ 0.2 µA to 4.0 µA

This setting is used to adjust the common mode current of the preamplifier.

Table 13: Trim Register 6 (write only)

Addr / CMD	0x1A (7 Bit!) / 0x08							
Trim Reg 6	7	6	5	4	3	2	1	0
Name	RFU			BPA TRIM BOT				

BPA_TRIM_BOT: 0 to 31 ⇒ 0.2 µA to 4.0 µA

This setting is used to adjust the common mode current of the preamplifier.

Table 14: Trim Register 7 (write only)

Addr / CMD	0x1A (7 Bit!) / 0x09							
Trim Reg 7	7	6	5	4	3	2	1	0
Name	PU SDA TRIM				PU SCL TRIM			

PU_SDA_TRIM: select internal pull up resistor on SDA
 PU_SCL_TRIM: select internal pull up resistor on SCL

“1000” = 100 kOhm; “0100” = 50 kOhm; “0010” = 10 kOhm; “0001” = 1 kOhm

Table 15: Read Data 1 Command (Top Half of Array)

Addr / CMD	0x1A (7 Bit!) / 0x0A							
Read Data	7	6	5	4	3	2	1	0
1. Byte / 2. Byte	PTAT 1 MSB / LSB or Vdd 1 MSB / LSB							
3. Byte / 4. Byte	Pixel (0+BLOCK*128) MSB / LSB							
5. Byte / 6. Byte	Pixel (1+BLOCK*128) MSB / LSB							
...	...							
257. Byte / 258. Byte	Pixel (127+BLOCK*128) MSB / LSB							

Table 16: Read Data 2 Command (Bottom Half of Array)

Addr / CMD	0x1A (7 Bit!) / 0x0B							
Read Data	7	6	5	4	3	2	1	0
1. Byte / 2. Byte	PTAT 2 MSB / LSB or Vdd 2 MSB / LSB							
3. Byte / 4. Byte	Pixel (992-BLOCK*128) MSB / LSB							
5. Byte / 6. Byte	Pixel (993-BLOCK*128) MSB / LSB							
...	...							
65. Byte / 66. Byte	Pixel (1023-BLOCK*128) MSB / LSB							
67. Byte / 68. Byte	Pixel (960-BLOCK*128) MSB / LSB							
69. Byte / 70. Byte	Pixel (961-BLOCK*128) MSB / LSB							
...	...							
129. Byte / 130. Byte	Pixel (991-BLOCK*128) MSB / LSB							
131. Byte / 132. Byte	Pixel (928-BLOCK*128) MSB / LSB							

...	
257. Byte / 258. Byte	Pixel (927-BLOCK*128) MSB / LSB

The complete sensor data must be read at once. If the communication fails somewhere in between, all successive data will be corrupted. The readout can be stopped anywhere by pausing the clock. A new initialized readout proceeds at this stopped byte by continuing the clock, but the index is reset when a new conversion has been started.

If the bit for the electrical offsets (Bit 1 in Config 0x01) is set the electrical offsets are sampled and can be read similar to the active pixel:

Table 17: Read Data Electrical Offsets (Top Half of Array)

Addr / CMD	0x1A (7 Bit!) / 0x0A							
Read Data	7	6	5	4	3	2	1	0
1. Byte / 2. Byte	PTAT 1 MSB / LSB or Vdd 1 MSB / LSB							
3. Byte / 4. Byte	electrical offset (0) MSB / LSB							
5. Byte / 6. Byte	electrical offset (1) MSB / LSB							
...	...							
257. Byte / 258. Byte	electrical offset (127) MSB / LSB							

Table 18: Read Data Electrical Offsets (Bottom Half of Array)

Addr / CMD	0x1A (7 Bit!) / 0x0B							
Read Data	7	6	5	4	3	2	1	0
1. Byte / 2. Byte	PTAT 2 MSB / LSB or Vdd 2 MSB / LSB							
3. Byte / 4. Byte	electrical offset (224) MSB / LSB							
5. Byte / 6. Byte	electrical offset (225) MSB / LSB							
...	...							
65. Byte / 66. Byte	electrical offset (255) MSB / LSB							
67. Byte / 68. Byte	electrical offset (192) MSB / LSB							
...	...							
257. Byte / 258. Byte	electrical offset (159) MSB / LSB							

The complete sensor data must be read at once. If the communication fails somewhere in between, all successive data will be corrupted. The readout can be stopped anywhere by pausing the clock. A new initialized readout proceeds at this stopped byte by continuing the clock, but the index is reset when a new conversion has been started.

Depending on the setting of VDD_MEAS the PTAT or the VDD is transmitted.

11.4 EEPROM Communication

The built-in EEPROM (24AA64 from Microchip) consists of 8 blocks of 1K x 8-bit. The chip select of the EEPROM is set to 000 (A2 to A0). For further information, please see the corresponding datasheet:

www.microchip.com

11.5 I²C Example Sequences – Init and Read Thermopile Array

(There should be a delay of at least 5 ms between the write of each Configuration Register)

Please be reminded, that you readout the calibration settings for MBIT, BIAS, CLK, BPA and PU and use them for a correct temperature calculation.

	ADDR	W/R	CONFIG_REG	WAKEUP	
S	0x1A	0	0x01	0x01	P

	ADDR	W/R	TRIM_REG1	MBIT_TRIM	
S	0x1A	0	0x03	0x0C	P

	ADDR	W/R	TRIM_REG2	BIAS_TRIML	
S	0x1A	0	0x04	0x0C	P

	ADDR	W/R	TRIM_REG3	BIAS_TRIMR	
S	0x1A	0	0x05	0x0C	P

	ADDR	W/R	TRIM_REG4	CLK_TRIM	
S	0x1A	0	0x06	0x14	P

	ADDR	W/R	TRIM_REG5	BPA_TRIML	
S	0x1A	0	0x07	0x0C	P

	ADDR	W/R	TRIM_REG6	BPA_TRIMR	
S	0x1A	0	0x08	0x0C	P

	ADDR	W/R	TRIM_REG7	PU_TRIM	
S	0x1A	0	0x09	0x88	P

	ADDR	W/R	CONFIG_REG	START WAKEUP	
S	0x1A	0	0x01	0x09	P

	ADDR	W/R	STATUS_REG		ADDR	W/R	STATUS	
S	0x1A	0	0x02	Sr	0x1A	1	??	P

Wait 30 ms

	ADDR	W/R	STATUS_REG		ADDR	W/R	STATUS	
S	0x1A	0	0x02	Sr	0x1A	1	??	P

	ADDR	W/R	READ_DATA 1		ADDR	W/R	PTAT1_MSB	PTAT1_LSB	P0,0_MSB	P0,0_LSB	...	Px,y_MSB	Px,y_LSB	
S	0x1A	0	0x0A	Sr	0x1A	1	??	??	??	??	...	??	??	P

	ADDR	W/R	READ_DATA 2		ADDR	W/R	PTAT2_MSB	PTAT2_LSB	P0,0_MSB	P0,0_LSB	...	Px,y_MSB	Px,y_LSB	
S	0x1A	0	0x0B	Sr	0x1A	1	??	??	??	??	...	??	??	P

	ADDR	W/R	CONFIG_REG	SLEEP	
S	0x1A	0	0x01	0x00	P

12 Temperature Calculation

The object and ambient temperature can be calculated from the sensor output and the stored calibration data. The table below is showing an overview of the EEPROM.

32x32d	0x00	0x01	0x02	0x03	0x04	0x05	0x06	0x07	0x08	0x09	0x0A	0x0B	0x0C	0x0D	0x0E	0x0F
0x0000	PixCmin (float)			PixCmax (float)			gradScale				TN as 16 bit unsigned		epsilon			
0x0010			Arraytype				VDDTH1		VDDTH2		MBIT(calib)		BIAS(calib)		CLK(calib) BPA(calib) PU(calib)	
0x0020					PTAT-gradient (float)		PTAT-offset (float)				PTAT (Th1)		PTAT (Th2)			
0x0030											VddScGrad		VddScOff			
0x0040					GlobalOff		GlobalGain									
0x0050					GlobalOff		GlobalGain									
0x0060	MBIT(user)		BIAS(user)		CLK(user)		BPA(user)		PU(user)							
0x0070					DeviceID										NrOfDefPix	
0x0080	DeadPixAdr as 16 bit unsigned values															
0x0090	DeadPixMask															
0x00A0	DeadPixMask															
0x00B0	free to use															
0x00C0	free to use															
0x00D0	free to use															
...																
0x0330	VddCompGrad _i stored as 16 bit signed values															
0x0340	VddCompGrad _i stored as 16 bit signed values															
...																
0x0530	VddCompOff _i stored as 16 bit signed values															
0x0540	VddCompOff _i stored as 16 bit signed values															
...																
0x0730	ThGrad _i stored as 16 bit signed values															
0x0740	ThGrad _i stored as 16 bit signed values															
...																
0x0F30	ThOffSet _i stored as 16 bit signed values															
0x0F40	ThOffSet _i stored as 16 bit signed values															
...																
0x1730	P _i stored as 16 bit unsigned values															
0x1740	P _i stored as 16 bit unsigned values															
...																
0x1F30																

Figure 11: EEPROM Overview 32x32d

All values are stored as unsigned 8-bit values unless they are specified otherwise. The little endian format is used for larger values. Grey marked areas are used during calibration or for future use and are Heimann Sensor reserved.

MBIT(calib), BIAS(calib), CLK(calib), BPA(calib) and PU(calib) are the settings for the registers, that have been used during calibration.

We recommend the usage of calibration settings of MBIT (stored in 0x1A), BIAS (0x1B), CLK (0x1c), BPA (0x1D) and PU (0x1E).

MBIT(user), BIAS(user), CLK(user), BPA(user) and PU(user) are free to be set by the user.

The temperature calculation is only valid, if the same settings are used that have been set during calibration!

TN is the table number and has to match the given table number in the sample code.

GlobalOff is stored as an 8-bit signed value, GlobalGain and VddCalib are both stored as 16 bit unsigned.

VDDTH1 and VDDTH2 is the used supply voltage during calibration measured by the sensor itself and stored in Digits.

The corresponding order of $ThGrad_{ij}$, $ThOffset_{ij}$ and P_{ij} to the Pixel number is given by the following overview:

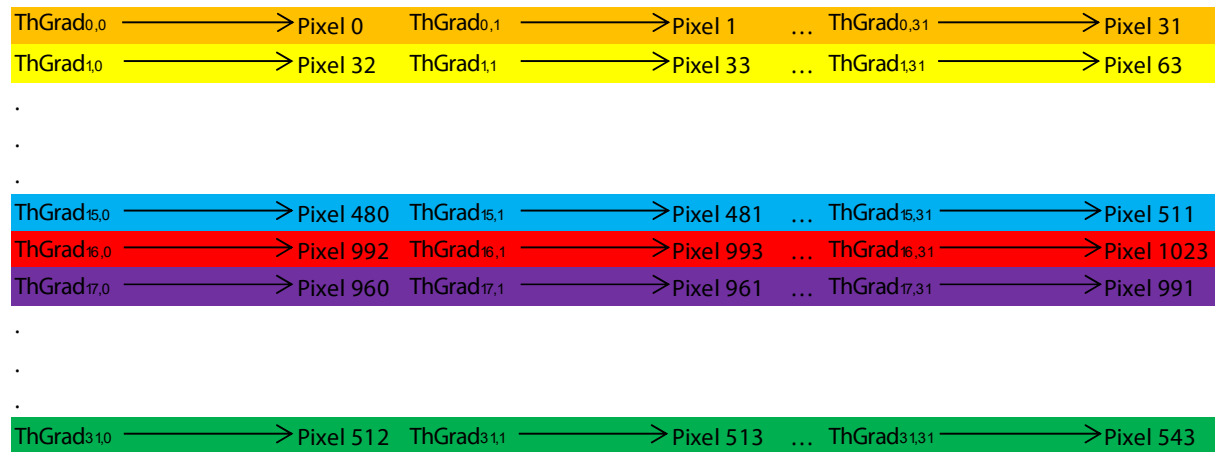


Figure 12: Readout Order 32x32d

The order of $VddCompGrad_{ij}$ and $VddCompOff_{ij}$ is similar to the electrical Offsets and have to be used block by block.

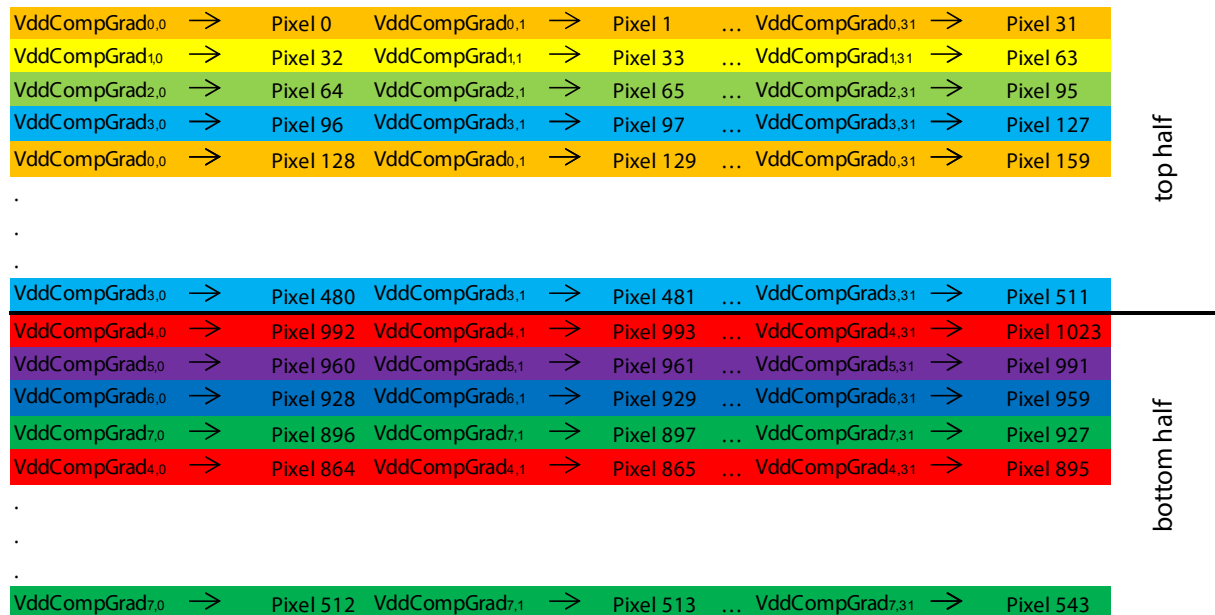


Figure 13: Readout of VDDCompGrad 32x32d

The order for DeadPixAdr_Pij is described more detailed in 13.1.

12.1 Ambient Temperature

The ambient temperature (T_a) is calculated from the average measured PTAT value, the $PTAT_{gradient}$ and the $PTAT_{offset}$. It is recommended to use a stack buffer for the PTAT values, in order to get a more stable ambient temperature result.

$$T_a = PTAT_{av} \cdot PTAT_{gradient} + PTAT_{offset} \quad (\text{Value is given back in dK})$$

where:

$PTAT_{gradient}$	is the gradient of the PTAT stored in the EEPROM as a float value
$PTAT_{offset}$	is the offset of the PTAT stored in the EEPROM as a float value
$PTAT_{av} = \frac{\sum_{i=0}^7 PTAT_i}{8}$	is the average measured PTAT value

12.2 Thermal Offset

The thermal offset of the sensor needs to be subtracted for each pixel to compensate for any thermal drifts.

$$V_{ij_Comp} = V_{ij} - \frac{ThGrad_{ij} \cdot PTAT_{av}}{2^{gradScale}} - ThOffset_{ij}$$

where:

ij	represents the row (i) and column (j) of the pixel
V_{ij_Comp}	is the thermal offset compensated voltage
V_{ij}	is the raw pixel data (digital), readout from the RAM
$ThGrad_{ij}$	is the thermal gradient, stored in the EEPROM from 0x740 to 0xF3F
$ThOffset_{ij}$	is the thermal offset, stored in the EEPROM from 0xF40 to 0x17F
$gradScale$	is the scaling coefficient for the thermal gradient stored in the EEPROM

12.3 Electrical Offset

The electrical offset is used to compensate changes in the supply voltage. This compensation is only a subtraction so it can be done before or after the thermal offset compensation (here done afterwards). It is recommended to use an electrical offset stack in order to get a more stable electrical offset result and a more stable temperature result at the end. The electrical offsets should be sampled every 8th to 10th frame.

The compensation for the top half is done by using the following formula:

$$V_{ij_Comp} *= V_{ij_Comp} - elOffset[(j + i \cdot 32)\%128]$$

and the bottom half analogue with this formula:

$$V_{ij_Comp} *= V_{ij_Comp} - elOffset[(j + i \cdot 32)\%128 + 128]$$

where:

ij	represents the row (i) and column (j) of the pixel and electrical offset
$V_{ij_Comp} *$	is the thermal and electrical offset compensated voltage
V_{ij_Comp}	is the thermal offset compensated voltage
$elOffset_{ij}$	is the electrical offset belonging to Pixel ij
$i\%128$	is the rest of the integer division of i by 128 (e.g. $130\%128=2$)

12.4 Vdd Compensation

A supply voltage compensation called VddComp is used to take care of supply voltage changes. In order to use this compensation the supply voltage of the sensor (Vdd) has to be measured by the sensor from time to time by setting the configuration register and the average of Vdd 1 and Vdd 2 is resulting in Vdd (similar like $PTAT_{av}$). It is recommended to use a VDD stack buffer in order to get a more stable VDD value. The stack should be similar to the PTAT stack.

The compensation for the top half is done by using the following formula:

$$VDD_{av} = \frac{\sum_{i=0}^7 VDD_i}{8}$$

$$V_{ijVDDComp} = V_{ijComp}*$$

$$\frac{\left(\frac{VddCompGrad[(j + i \cdot 32)\%128] \cdot PTAT_{av}}{2^{VDDScGrad}} + VddCompOff[(j + i \cdot 32)\%128] \right)}{2^{VDDScOff}} \cdot \left(VDD_{av} - VDD_{TH1} - \left(\frac{VDD_{TH} - VDD_{TH1}}{PTAT_{TH} - PTAT_{TH1}} \right) \cdot (PTAT_{av} - PTAT_{TH1}) \right)$$

and the bottom half analogue with this formula:

$$V_{ijVDDComp} = V_{ijComp}*$$

$$\frac{\left(\frac{VddCompGrad[(j + i \cdot 32)\%128 + 128] \cdot PTAT_{av}}{2^{VDDScGrad}} + VddCompOff[(j + i \cdot 32)\%128 + 128] \right)}{2^{VDDScOff}} \cdot \left(VDD_{av} - VDD_{TH1} - \left(\frac{VDD_{TH} - VDD_{TH1}}{PTAT_{TH} - PTAT_{TH1}} \right) \cdot (PTAT_{av} - PTAT_{TH1}) \right)$$

where:

ij	represents the row (i) and column (j) of the pixel
$V_{ij_VDDComp}$	is the Vdd compensated voltage

$V_{ij_Comp}^*$	is the thermal and electrical offset compensated voltage
$VddComGrad[ij]$	is the VddComp gradient belonging to Pixel ij
$VddComOff[ij]$	is the VddComp offset belonging to Pixel ij
$i\%128$	is the rest of the integer division of i by 128 (e.g. $130\%128=2$)
VDD_{av}	is the average measured supply voltage of the sensor in Digits
$VddScGrad$	is a scaling coefficient and stored in the EEPROM 0x4E
$VddScOff$	is a scaling coefficient and stored in the EEPROM 0x4F
VDD_{TH1}	is the supply voltage during calibration 1 stored in the EEPROM 0x26, 0x27
VDD_{TH2}	is the supply voltage during calibration 2 stored in the EEPROM 0x28, 0x29
$PTAT_{TH1}$	is the PTAT value of calibration 1 stored in the EEPROM 0x3C, 0x3D
$PTAT_{TH2}$	is the PTAT value of calibration 2 stored in the EEPROM 0x3E, 0x3F

12.5 Object Temperature

The calculation of the object temperature is done by using a look-up table and doing a bi-linear interpolation, the matching table is given by the table number (TN). The table is supplied in a separate file named "Table.c". If you do not have the file, please ask Heimann Sensor for support.

The sensitivity coefficients ($PixC_{ij}$) are calculated in the following way:

$$PixC_{ij} = \left(\frac{P_{ij} \cdot (PixC_{max} - PixC_{min})}{65535} + PixC_{min} \right) \cdot \frac{\epsilon}{100} \cdot \frac{GlobalGain}{10000}$$

where:

$PixC_{ij}$	is the sensitivity coefficient for each pixel
P_{ij}	is the stored sensitivity coefficient scaled to 16 bit
$PixC_{min}$	is the minimum sensitivity coefficient, used for scaling
$PixC_{max}$	is the maximum sensitivity coefficient, used for scaling
ϵ	is the emissivity factor
$GlobalGain$	is a factor for fine tuning of the sensitivity for all Pixel

Leading to a compensation of the pixel voltage

$$V_{ij_PixC} = \frac{V_{ij_VDDComp} \cdot PCSCALEVAL}{PixC_{ij}}$$

where:

V_{ij_PixC}	is the sensitivity compensated IR voltage
$PCSCALEVAL$	is a defined scaling coefficient, typically set to $1 \cdot 10^8$

13 Example Calculation

Example values:

$$PTAT_{av} = \frac{\sum_{i=0}^7 PTAT_i}{8} = 38152 \text{Digits}$$

$$PTAT_{gradient} = 0.0211 \text{ dK/Digit}$$

$$PTAT_{offset} = 2195.0 \text{ dK}$$

$$V_{00} = 34435 \text{ Digits}$$

$$elOffset[0] = 34240$$

$$gradScale = 17$$

$$THGrad_{00} = 87 \rightarrow \text{signcheck } 87$$

$$THOffset_{00} = 65506 \rightarrow \text{signcheck } - 30$$

$$VDD_{av} = 35000$$

$$VDD_{TH} = 33942$$

$$VDD_{TH2} = 36942$$

$$PTAT_{TH} = 30000$$

$$PTAT_{TH2} = 42000$$

$$VddCompGrad[0] = 10356 \rightarrow \text{signcheck } 10356$$

$$VddCompOff[0] = 51390 \rightarrow \text{signcheck } - 14146$$

$$VddScGrad = 16$$

$$VddScOff = 23$$

$$PixC_{00} = 1 \cdot 10^8$$

$$PCSCALEVAL = 1 \cdot 10^8$$

Calculation of ambient temperature:

$$T_a = PTAT_{av} \cdot PTAT_{gradient} + PTAT_{offset} = 38152 \cdot 0.0211 + 2195.0 \text{ dK} = 3000 \text{ dK}$$

Compensation of thermal offset:

$$V_{00_Comp} = V_{00} - \frac{ThGrad_{00} \cdot PTAT_{av}}{2^{gradScale}} - ThOffset_{00} = 34435 - \frac{87 \cdot 38152}{2^{17}} - (-30) = 34439$$

Compensation of electrical offset:

$$V_{00_Comp}^* = V_{00_Comp} - elOffset[0] = 34439 - 34240 = 199$$

Compensation of supply voltage:

$$V_{ij_VDDComp} = V_{ij_Comp}^* - \frac{\left(\frac{VddCompGrad[0] \cdot PTAT_{av}}{2^{VddScGrad}} + VDDCompOff[0] \right)}{2^{VddScOff}}$$

$$\cdot \left(VDD_{av} - VDD_{Th1} - \left(\frac{VDD_{TH} - VDD_{TH}}{PTAT_{TH2} - PTAT_{TH1}} \right) \cdot (PTAT_{av} - PTAT_{TH}) \right)$$

$$= 199 - \frac{\left(\frac{10356 \cdot 38152}{2^{16}} - 14146 \right) \cdot (35000 - 33942 \pm 2038)}{2^{23}} = 199 - (1) = 198$$

Table 19: Example look-up table

TA[dK]/dig	2882	3032	3182	3332
-64	1494	2128	2491	2775
-32	2466	2692	2898	3091
0	2882	3032	3182	3332
32	3170	3285	3406	3530
64	3396	3491	3592	3699
96	3584	3665	3754	3848
128	3746	3818	3897	3981
160	3890	3954	4025	4102
192	4019	4078	4143	4214
224	4137	4191	4251	4317
256	4246	4296	4351	4413
288	4347	4393	4445	4503
320	4441	4485	4534	4588

$$V_{00_PixC} = \frac{198 \cdot 1 \cdot 10^8}{1.087 \cdot 10^8} = 182$$

Ta was calculated before to 3000 dK.

The matching region in the look-up table is already marked yellow, the bi-linear interpolation is leading to an object temperature of 4026 dK = (4026dK-2732dK)/10 = 129.4 °C.

A global Offset (GlobalOff) is used for fine tuning of the measured object temperature and has to be added to the object temperature. This value is stored in the EEPROM.

13.1 Pixel Masking

A maximum of 5 defect Pixels are allowed on the complete array, this means that at least 99.5 % of the Pixels are working correctly. The amount of defect Pixels is given in the EEPROM at address 0x007F and is named *NrOfDefPix*. *DeadPixAdr* is the address of the defect Pixels and *DeadPixMask* determines the neighbours, that should be used for masking the pixel. A simple averaging of all selected nearest neighbours is done to overwrite the temperature value of these Pixel. Only the amount of pixels "*NrOfDefPix*" is stored in *DeadPixAdr*. These values are stored as 16 bit unsigned values. For example: If only one pixel has to be masked, then the other values of *DeadPixAdr* are set to 0.

The value stored in *DeadPixAdr* is equal to the pixel number if *DeadPixAdr* is <0x0200. If the value is greater, that means between 0d512 and 0d1024, the actual read-out pixel has to be calculated first. For example: If you have a pixel number of 997 stored to the EEPROM, this is actually 517 (please refer to 6). The pixel number, that is stored in the EEPROM corresponds to the number of the read-out pixel. So the bottom half is mirrored.

Example calculation:

$$adaptedAdr [i] = 1024 + 512 - DeadPixAdr [i] + k[i] \cdot 2 - 32$$

where:

adaptedAdr [i] is the adapted dead pixel address

k[i] is the column of the corresponsive pixel (for pixel number 997 this would be 5)

$$adaptedAdr [i] = 1024 + 512 - 997 + 10 - 32 = 517$$

The neighbours to use is given in a binary format and the order is shown in the overview below in decimal and binary values for the top and bottom half.

top half

128	1	2
64	DeadPix	4
32	16	8

0b1000 0000	0b0000 0001	0b0000 0010
0b0100 0000	DeadPix	0b0000 0100
0b0010 0000	0b0001 0000	0b0000 1000

bottom half

32	16	8
64	DeadPix	4
128	1	2

0b0010 0000	0b0001 0000	0b0000 1000
0b0100 0000	DeadPix	0b0000 0100
0b1000 0000	0b0000 0001	0b0000 0010

Example values for the masking:

$$NrOfDefPix = 0x03$$

$$DeadPixAdr[0] = 0x000F \rightarrow \text{Pixel 15}$$

$$DeadPixAdr[1] = 0x012C \rightarrow \text{Pixel 300}$$

$$DeadPixAdr[2] = 0x0295 \rightarrow \text{Pixel 661 (read – out pixel) actual pixel number is 885}$$

$$DeadPixMask[0] = 0x7C \rightarrow 0b01111100(\text{top})$$

$$DeadPixMask[1] = 0x8F \rightarrow 0b10001111(\text{top})$$

$$DeadPixMask[2] = 0xFE \rightarrow 0b11111110(\text{bot})$$

According to the sample values 3 Pixels are defect and need to be interpolated. 2 Pixels are on the top and 1 Pixel on the bottom half. Assuming, that the neighbouring Pixels are having the temperature data stated below and the green marked cells are used for averaging (according to DeadPixMask), then the interpolated temperature will be the following:

$$Pixel\ 15 = \frac{3007 + 3008 + 3008 + 3011 + 3009}{5} dK = \frac{15043}{5} dK \approx 3009dK$$

$$Pixel\ 300 = \frac{3010 + 3012 + 3005 + 3008 + 3009}{5} dK = \frac{15044}{5} dK \approx 3009dK$$

$$Pixel\ 885 = \frac{3010 + 3012 + 3005 + 3007 + 3008 + 3008 + 3009}{7} dK = \frac{21059}{7} dK \approx 3008dK$$

All values are given in dK

3007	Pixel 15	3008
3008	3011	3009

Pixel 14	Pixel 15	Pixel 16
Pixel 46	Pixel 47	Pixel 48

3010	3012	3005
3007	Pixel 300	3008
3008	3011	3009

Pixel 267	Pixel 268	Pixel 269
Pixel 299	Pixel 300	Pixel 301
Pixel 331	Pixel 332	Pixel 333

3010	3012	3005
3007	Pixel 885	3008
3008	3011	3009

Pixel 852	Pixel 853	Pixel 854
Pixel 884	Pixel 885	Pixel 886
Pixel 916	Pixel 917	Pixel 918

If a pixel is masked, the adjacent neighbours must have not more than 4 dead pixels in serial order, if you check them clockwise (or the other way around):

OK		
0	1	0
0	0	1
1	0	0

OK		
0	1	0
0	0	1
0	0	1

NOK		
0	1	1
0	0	1
0	0	0

13.2 Look-up Table

The matching look-up table has to be taken from the "Table.c" file. Here is just shown an exemplary data for one optic.

Table with 10 columns and 1000 rows of numerical data. The first column is labeled 'dig. I, Tai[dK]'. Values range from -512 to 6794.

Table with 10 columns and 1000 rows of numerical data. Values range from 6848 to 14208.

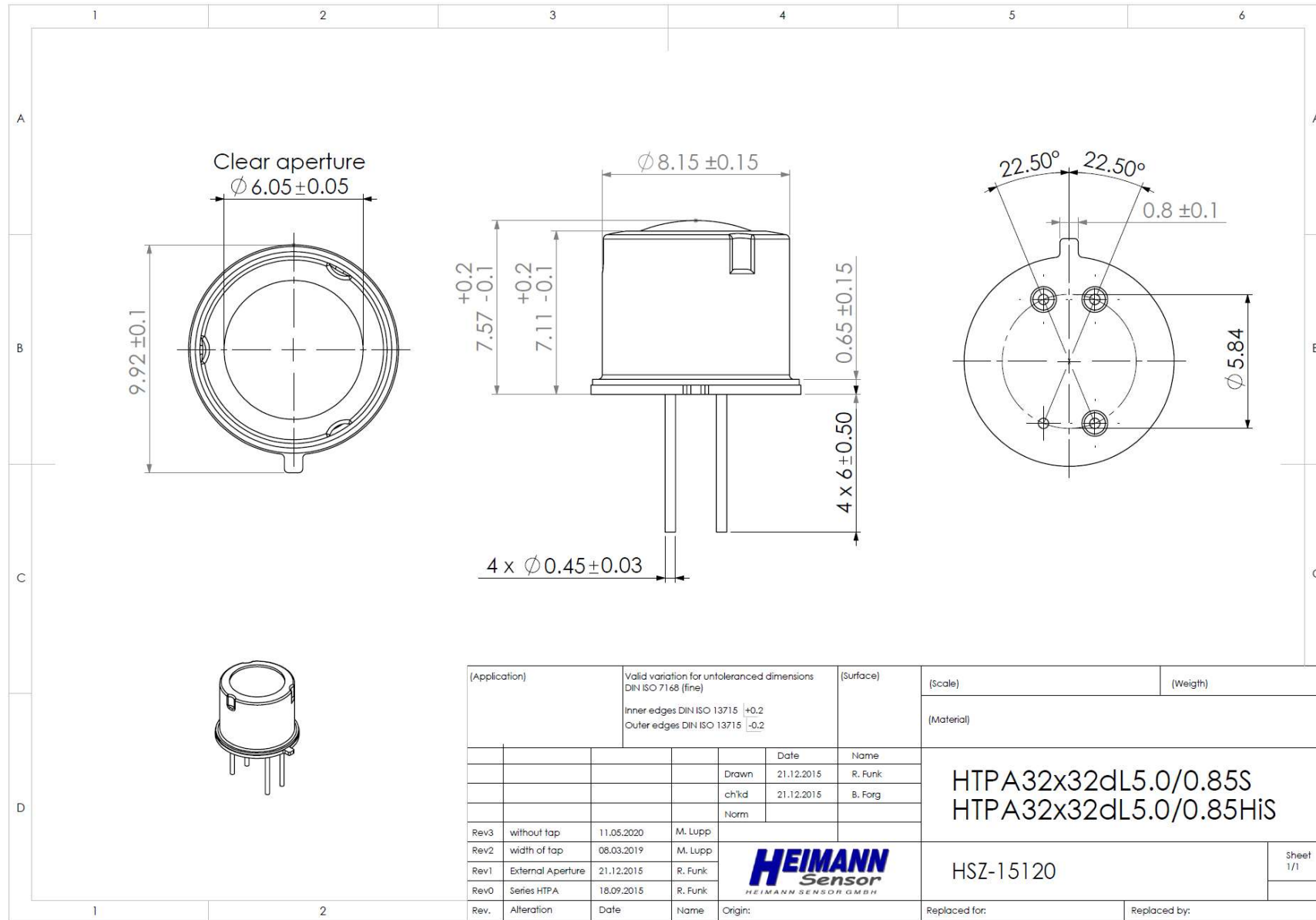
14 Order Code Chart

HTPA32x32d	R2	L5.0/0.85	F7.7	e	Hi	A	(USB)
HTPA32x32d	R2	L5.0/0.85	F7.7	e	Hi	A	(UDP)
HTPA32x32d	R2	L5.0/0.85	F7.7	e	Hi	M	(UDP)
HTPA32x32d	R2	L5.0/0.85	F7.7	e	Hi	C	
HTPA32x32d	R2	L2.1/0.8	F5.0		Hi	A	(USB)
HTPA32x32d	R2	L2.1/0.8	F5.0		Hi	A	(UDP)
HTPA32x32d	R2	L2.1/0.8	F5.0		Hi	M	(UDP)
HTPA32x32d	R2	L2.1/0.8	F5.0		Hi	C	
HTPA32x32d	R2	L1.6/0.8	F5.0		Hi	A	(USB)
HTPA32x32d	R2	L1.6/0.8	F5.0		Hi	A	(UDP)
HTPA32x32d	R2	L1.6/0.8	F5.0		Hi	M	(UDP)
HTPA32x32d	R2	L1.6/0.8	F5.0		Hi	C	
HTPA32x32d	R2	L2.85/1			Hi	A	(USB)
HTPA32x32d	R2	L2.85/1			Hi	A	(UDP)
HTPA32x32d	R2	L2.85/1			Hi	M	(UDP)
HTPA32x32d	R2	L2.85/1			Hi	C	
HTPA32x32d	R2	L1.9/0.8			Hi	A	(USB)
HTPA32x32d	R2	L1.9/0.8			Hi	A	(UDP)
HTPA32x32d	R2	L1.9/0.8			Hi	M	(UDP)
HTPA32x32d	R2	L1.9/0.8			Hi	C	
HTPA32x32d	R2	L1.8/0.8			Hi	A	(USB)
HTPA32x32d	R2	L1.8/0.8			Hi	A	(UDP)
HTPA32x32d	R2	L1.8/0.8			Hi	M	(UDP)
HTPA32x32d	R2	L1.8/0.8			Hi	C	
HTPA32x32d	R2	L1.7/0.8			Hi	A	(USB)
HTPA32x32d	R2	L1.7/0.8			Hi	A	(UDP)
HTPA32x32d	R2	L1.7/0.8			Hi	M	(UDP)
HTPA32x32d	R2	L1.7/0.8			Hi	C	

Bold: Selectable options

Regular: Fixed/Not selectable

15 Outer Dimensions

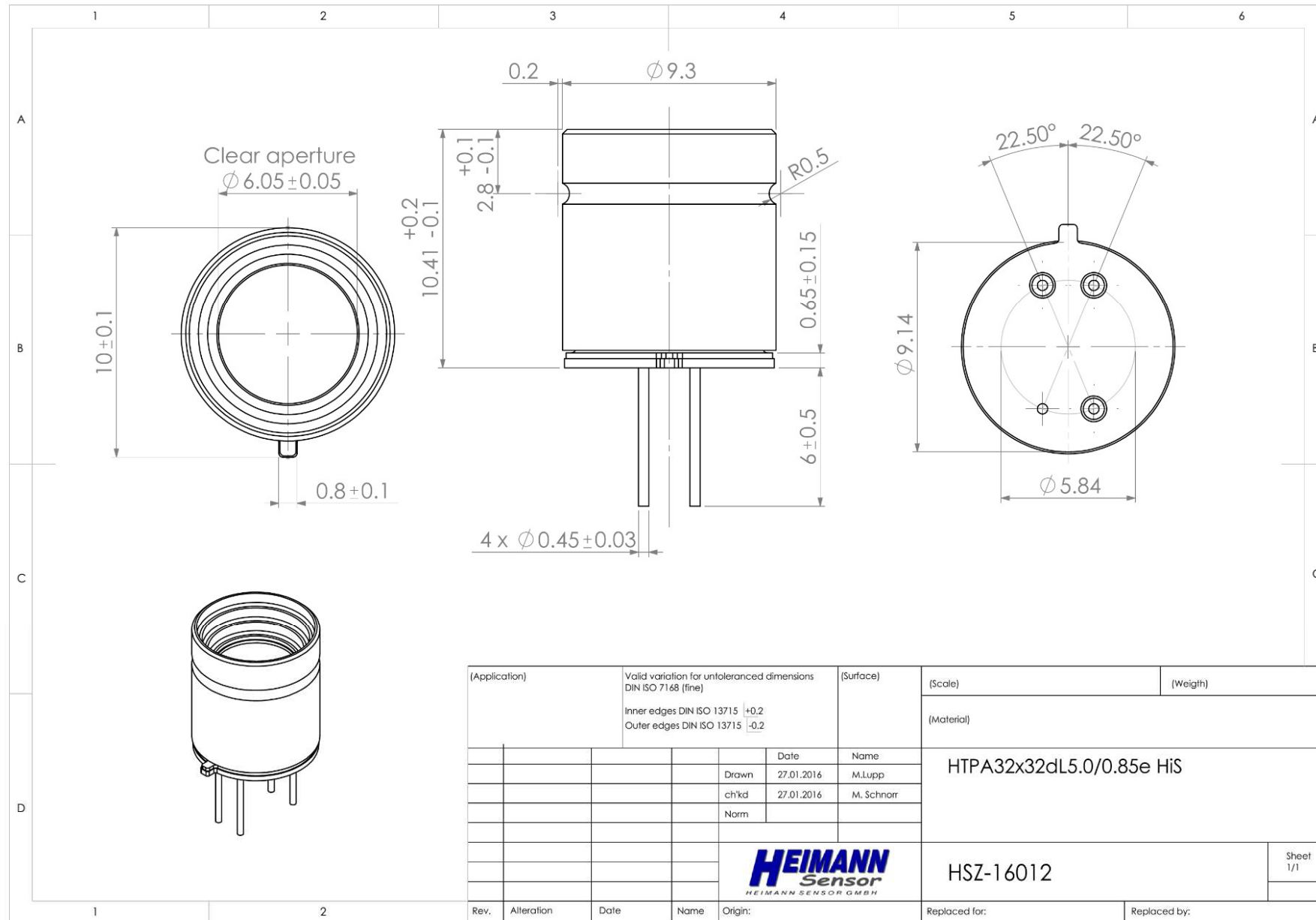


(Application)		Valid variation for untoleranced dimensions DIN ISO 7168 (fine)		(Surface)		(Scale)	(Weight)
		Inner edges DIN ISO 13715 +0.2 Outer edges DIN ISO 13715 -0.2				(Material)	
				Date	Name	HTPA32x32dL5.0/0.85S HTPA32x32dL5.0/0.85HiS	
				Drawn	R. Funk		
				ch'kd	B. Forg		
				Norm			
Rev3	without tap	11.05.2020	M. Lupp				
Rev2	width of tap	08.03.2019	M. Lupp				
Rev1	External Aperture	21.12.2015	R. Funk				
Rev0	Series HTPA	18.09.2015	R. Funk				
Rev.	Alteration	Date	Name	Origin:			
						Replaced for:	Replaced by:



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Sheet 1/1



(Application)		Valid variation for untoleranced dimensions DIN ISO 7168 (fine)		(Surface)		(Scale)		(Weight)		
		Inner edges DIN ISO 13715 +0.2 Outer edges DIN ISO 13715 -0.2				(Material)				
				Date	Name	HTPA32x32dL5.0/0.85e HiS				
				Drawn 27.01.2016	M.Lupp					
				ch'kd 27.01.2016	M. Schnorr					
				Norm						
						HSZ-16012			Sheet 1/1	
Rev.	Alteration	Date	Name			Origin:	Replaced for:	Replaced by:		